


PRODUCT / PROCESS CHANGE NOTIFICATION

1. PCN basic data

1.1 Company		STMicroelectronics International N.V
1.2 PCN No.	MDG/16/9640	
1.3 Title of PCN	Transfer of assembly plant from STATS ChipPAC Shanghai (China) to Amkor ATP (Philippines) - Products in VFQFPN 36 6x6 package	
1.4 Product Category	Products in VFQFPN 36 6x6 package	
1.5 Issue date	2016-07-08	

2. PCN Team

2.1 Contact supplier	
2.1.1 Name	SETTLES JEFF
2.1.2 Phone	+44 1628896222
2.1.3 Email	jeff.settles@st.com
2.2 Change responsibility	
2.2.1 Product Manager	Michel BUFFA
2.1.2 Marketing Manager	Daniel COLONNA
2.1.3 Quality Manager	Pascal NARCHE

3. Change

3.1 Category	3.2 Type of change	3.3 Manufacturing Location
Transfer of a full process or process brick (process step, control plan, recipes) from one site to another site	Assembly site	STATS ChipPAC Shanghai (China), Amkor ATP (Philippines)

4. Description of change

	Old	New
4.1 Description	Previous assembly plant : STATS ChipPAC Shanghai (China) Previous Bill Of Materials: - Resin : G770 - Die attach material : Ablebond 8290	Transfer to new assembly plant : Amkor ATP (Philippines) New Bill Of Materials: - Resin : G700Y - Die attach material : Dexter 1234-100
4.2 Anticipated Impact on form,fit, function, quality, reliability or processability?	no change	

5. Reason / motivation for change

5.1 Motivation	Rationalization of Microcontroller packages manufacturing through a centralization of VFQFPN in Amkor ATP (Philippines) production site.
5.2 Customer Benefit	SERVICE IMPROVEMENT

6. Marking of parts / traceability of change

6.1 Description	See in 9640_Additional information document attached.
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7. Timing / schedule

7.1 Date of qualification results	2016-09-07
7.2 Intended start of delivery	2016-10-07
7.3 Qualification sample available?	Upon Request

8. Qualification / Validation

8.1 Description	PCN9640 - RER1607MCD reliability plan for ATP VQFN6X6 new project.pdf		
8.2 Qualification report and qualification results	Available (see attachment)	Issue Date	2016-07-08

9. Attachments (additional documentations)

9640PpPrdtLst.pdf
9640_Additional information.pdf
PCN9640 - RER1607MCD reliability plan for ATP VQFN6X6 new project.pdf

10. Affected parts

10. 1 Current		10.2 New (if applicable)
10.1.1 Customer Part No	10.1.2 Supplier Part No	10.1.2 Supplier Part No
	STM32F103TBU6	

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